

Title (en)

SOLDER ALLOY, SOLDERING METHOD AND COMPONENT

Title (de)

LOTLEGIERUNG, LOTVERFAHREN UND BAUTEIL

Title (fr)

ALLIAGE DE BRASAGE, PROCÉDÉ DE BRASAGE ET PIÈCE CORRESPONDANTE

Publication

EP 2558244 A2 20130220 (DE)

Application

EP 10713921 A 20100412

Priority

EP 2010054756 W 20100412

Abstract (en)

[origin: US2013045129A1] A solder alloy including a base material, a solder, and an additive is provided. The solder alloy has the following formula: $(1-x-y) \cdot \text{base material} + x \cdot \text{solder} + y \cdot \text{additive}$, where $0.2 \leq x \leq 0.8$ and $0 \leq y < 0.8$ and also $(y < 1-x) < (1-x)$. The base material includes chromium, cobalt, aluminum, and tungsten. The solder includes chromium, cobalt, aluminum, tungsten, germanium and/or gallium and nickel. The additive may include boron, zirconium, hafnium, niobium, and carbon.

IPC 8 full level

B23K 35/00 (2006.01); **F01D 5/00** (2006.01)

CPC (source: EP US)

B23K 35/30 (2013.01 - EP US); **F01D 5/005** (2013.01 - EP US); **F05D 2230/238** (2013.01 - EP US); **Y02T 50/60** (2013.01 - US)

Citation (search report)

See references of WO 2011127958A2

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